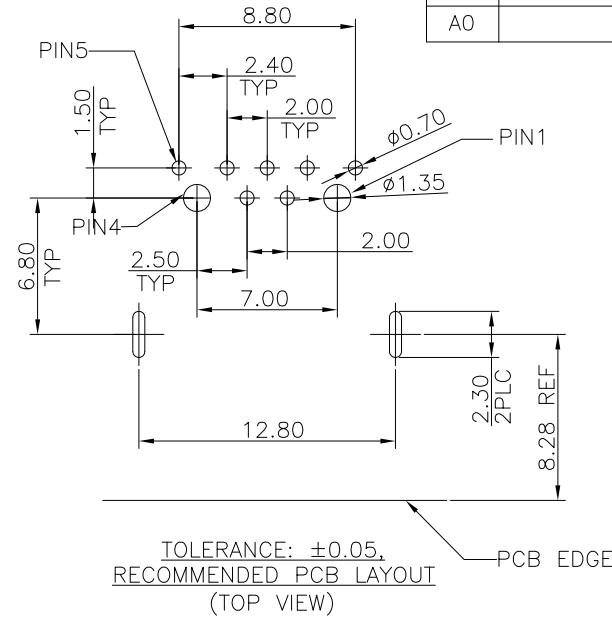
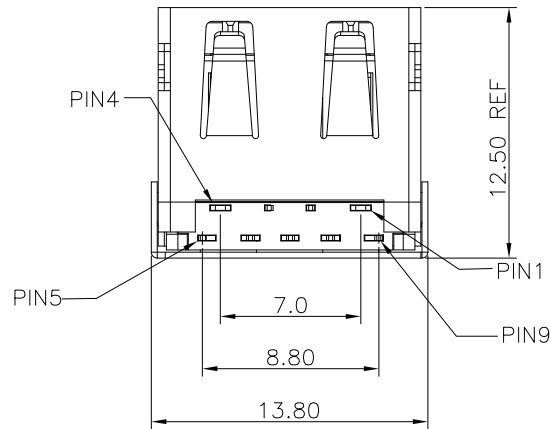
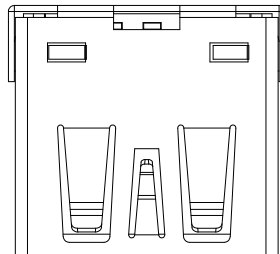
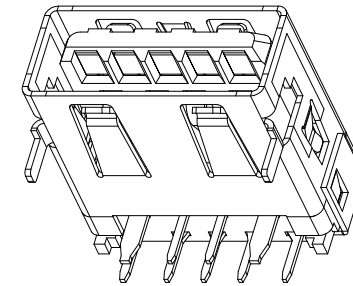
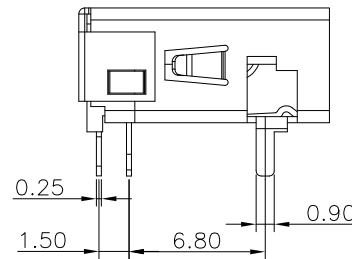
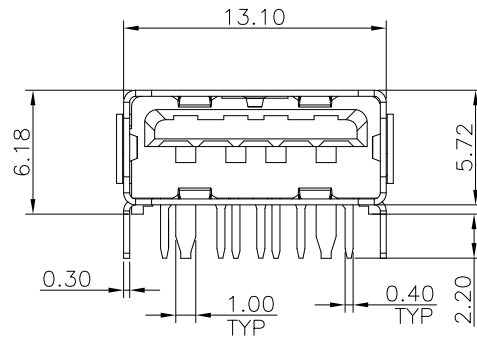


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2014/07/03	Phebe Su



- NOTES:
- 1.MATERIAL:
 - 1.1 HOUSING: HIGH TEMPERATURE THERAL PLASTIC, BLUE
 - 1.2 CONTACT: COPPER ALLOY.
 - 1.3 SHELL: STEEL.
 - 2.FINISH:
 - 2.1 CONTACT:GOLD FLASH ON CONTACT AREA/100u" Min MATTE TIN ON SOLDER AREA .50u" MIN. NICKEL UNDERPLATING OVER ALL.
 - 2.2 SHELL: 50u" MIN.NICKEL UNDERPLATING OVER ALL.
 - 3.Characteristics:
 - 3.1 Rating Voltage : 30V
 - 3.2 Rating Current : 5.0 AMP
 - 3.3 Contact Resistance : 30 mΩ MAX.
 - 3.4 Insulation Resistance: 1000 MΩ MIN.
 - 3.5 Withstanding Voltage :AC 500V
 - 3.6 Mating force: 3.57KgF MAX(35N MAX)
 - 3.7 Extraction force: 1.02KgF Min(10N Min)
 - 3.8 Life test:1500 Cycles MIN.
 - 3.9 Temperature Range: -55°C~+85°C.



MATRIX PART NO:

MUSB - 09 - 01 - 68

MATRIX USB Pin Number Series number

Planting
01:Gold Flash
15:15u"
30:30u"



Matrix Electronics Co.,Ltd

TOLERANCE: X:X X:XX X:XXX ANGLE: ±3°	DESIGN BY : Phebe Su	DATE : 2014/07/03	PART NAME: USB3.0 SHORT DIP FEMALE	
UNIT: mm [inch]	CHECKED BY: Vicky Hsieh	DATE : 2014/07/03	PART NO.	MUSB09-01-68
SCALE:1:1	APPROVED BY1: Richard Hsieh	DATE : 2014/07/03	MOLD NO.	NA
SIZE:A4	APPROVED BY2: Richard Hsieh	DATE : 2014/07/03	DRAW NO.	
			SHEET NO.	1 OF 1